

| L Number | Hits | Search Text  | DB  | Time stamp       |
|----------|------|--|---|------------------|
| 1        | 758  | 374/208.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/23 20:47 |
| 2        | 526  | 374/183.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/23 20:48 |
| 3        | 171  | 374/158.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/23 20:48 |
| 4        | 1109 | 600/549.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/23 20:48 |
|          | 719  | 374/208.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/23 14:51 |
|          | 501  | 374/183.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/03 12:13 |
|          | 1022 | 600/549.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/16 17:28 |
|          | 300  | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and calibration  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 11:43 |
|          | 20   | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and calibration and memory and (removable or detachable) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/08 15:05 |
|          | 107  | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and calibration and memory                               | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/08 16:58 |
|          | 27   | "167876"   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/08 17:01 |
|          | 14   | "2183342"  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/08 17:03 |

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|  | 3   | "9813677"  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/09 16:19 |
|  | 18  | "4008614"  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/08 17:08 |
|  | 22  | "3318977"  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/08 17:08 |
|  | 0   | (probe and tip and isolation and algorithm).ti.                              | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/09 10:25 |
|  | 395 | 374/1.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/09 16:15 |
|  | 91  | 374/2.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/09 16:16 |
|  | 53  | 374/3.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/09 16:16 |
|  | 165 | 374/158.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/09 16:20 |
|  | 26  | "5347476"  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/15 12:15 |
|  | 2   | 5347476.pn.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/15 12:49 |
|  | 2   | 5794625.pn.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/15 12:49 |
|  | 4   | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and EEPROM and encapsul\$8 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 14:18 |

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|  | 3     | "9813677"   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 13:43 |
|  | 159   | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and resistant                       | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 14:18 |
|  | 74    | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and resistant and seal\$3           | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 14:19 |
|  | 1     | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and overmold                        | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 14:19 |
|  | 119   | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and encapsulated                    | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 14:20 |
|  | 31    | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and encapsulated and fluid          | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 14:20 |
|  | 1     | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and (fluid near resistant)          | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/17 09:41 |
|  | 3     | "6179785"   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 14:37 |
|  | 22521 | water adj resistant   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 14:38 |
|  | 184   | (water adj resistant) and (electrical adj connector)                                  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 11:59 |
|  | 17    | (water adj resistant) and (electrical adj connector) and (encapsulated or overcoated) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/16 14:52 |
|  | 17    | (water adj resistant) and (electrical adj connector) and (encapsulated or overcoat)   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 11:42 |

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|  | 479   | (water adj resistant) and thermometer   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 11:43 |
|  | 480   | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and seal\$4   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 11:45 |
|  | 328   | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and seal\$4 and (water or fluid or liquid)            | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 11:55 |
|  | 28    | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and seal\$4 and (water or fluid or liquid) and module | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 11:55 |
|  | 18553 | (seal\$5 or coat\$3 or overcoat\$4) and (electrical adj connector)                                      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 12:00 |
|  | 7168  | (seal\$5 or coat\$3 or overcoat\$4) and (electrical adj (terminal))                                     | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 12:02 |
|  | 5350  | (seal\$5) and (electrical adj (terminal))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 12:02 |
|  | 3128  | (seal\$5) and (electrical adj (terminal)) and (fluid or water or liquid)                                | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 12:03 |
|  | 49    | (seal\$5) and (electrical adj (terminal)) and ((fluid or water or liquid) adj resistant)                | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 12:07 |
|  | 296   | (seal\$5) and (electrical adj (contact)) and ((fluid or water or liquid) adj resistant)                 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 12:14 |
|  | 393   | (electrical adj (contact)) and (water near resistant)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 12:15 |
|  | 0     | (electrical adj (contact)) NEAR (water near resistant)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2002/10/17 12:15 |

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|  | 60   | (electrical adj (terminal)) and (water near resistant)       | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 12:16 |
|  | 0    | (electrical adj (terminal)) NEAR (water near resistant)      | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 12:16 |
|  | 6    | (terminal) NEAR (water near resistant)                       | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 12:18 |
|  | 142  | chip and overmold  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 12:22 |
|  | 2381 | chip and (water adj (proof or resistan\$3))                  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 12:23 |
|  | 4675 | circuit and (water adj (proof or resistan\$3))               | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 12:23 |
|  | 8    | circuit adj (water adj (proof or resistan\$3))               | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 12:27 |
|  | 112  | board adj (water adj (proof or resistan\$3))                 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 12:56 |
|  | 1    | (circuit adj board) adj (water adj (proof or resistan\$3))   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 13:06 |
|  | 1313 | (circuit adj board) and (water adj (proof or resistan\$3))   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 13:07 |
|  | 2    | (circuit adj board) near (water adj (proof or resistan\$3))  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 13:08 |
|  | 1    | (circuit adj board) near (liquid adj (proof or resistan\$3)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 13:14 |

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|  | 58   | (circuit adj board) and (liquid adj (proof or resistan\$3))                                    | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 13:10 |
|  | 1372 | (circuit adj board) and (overcoat\$4)  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 13:14 |
|  | 892  | (circuit adj board) and (overcoat\$4) and protect\$5   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 13:16 |
|  | 6    | ((circuit adj board) NEAR (overcoat\$4)) and protect\$5  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 14:33 |
|  | 0    | ((circuit adj board) NEAR (overcoat\$4)) and protect\$5 and memory                             | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 14:34 |
|  | 213  | (circuit adj board) and memory and (overcoat\$4) and protect\$5                                | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 14:35 |
|  | 48   | (circuit adj board) and (memory adj chip) and (overcoat\$4) and protect\$5                     | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 15:00 |
|  | 14   | (circuit adj board) and (memory adj chip) and (overcoat\$4) and protect\$5 and moisture        | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 15:12 |
|  | 63   | "4821148"  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 15:12 |
|  | 176  | (circuit adj board) and (connection or terminal) and (overcoat\$4) and protect\$5 and moisture | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 15:20 |
|  | 7    | (circuit adj board) and (EEPROM) and (overcoat\$4) and protect\$5 and moisture                 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 15:21 |
|  | 27   | (water adj proof) and EEPROM   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 15:24 |

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|  | 3270 | (water adj proof) and (circuit board)                                     | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:18 |
|  | 803  | (water adj proof) and (circuit board) and terminal                        | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 15:34 |
|  | 150  | (water adj proof) and (circuit board)and (overcoat\$3 or encapsulat\$3)   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 15:40 |
|  | 150  | (water adj proof) and (circuit board) and (overcoat\$3 or encapsulat\$3)  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:06 |
|  | 344  | (water adj proof) adj connector   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:15 |
|  | 17   | ((water adj proof) adj connector) and (circuit adj board)                 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 15:58 |
|  | 83   | (water adj proof) and (connector) and (overcoat\$3 or encapsulat\$3)      | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:08 |
|  | 9    | ((water adj proof) adj (connector)) and (overcoat\$3 or encapsulat\$3)    | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:10 |
|  | 10   | ((water adj proof\$3) adj (connector)) and (overcoat\$3 or encapsulat\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:13 |
|  | 10   | "5527989"   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:12 |
|  | 2    | "6376914"   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:12 |
|  | 10   | ((water adj proof\$3) adj (connector)) and (overcoat\$3 or encapsulat\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:13 |

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|  | 12  | (water adj proof) adj contact  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:16 |
|  | 120 | (water adj proof\$3) NEAR (circuit board)                              | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:25 |
|  | 2   | (water adj proof\$3) NEAR (circuit adj board)                          | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:25 |
|  | 40  | ((water adj proof\$3) NEAR (connector)) and (coating or layer)         | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:37 |
|  | 0   | ((water adj proof\$3) NEAR (connector adj pin)) and (coating or layer) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:27 |
|  | 0   | ((water adj proof\$3) NEAR (connector adj pin))                        | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:28 |
|  | 0   | ((water adj proof\$3) NEAR (connector adj contact))                    | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:28 |
|  | 18  | ((water adj proof\$3) and (connector adj contact))                     | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:47 |
|  | 86  | ((water adj proof\$3) and (contact adj terminal))                      | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/10/17 16:48 |
|  | 733 | 374/208.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/16 17:21 |
|  | 513 | 374/183.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/16 15:28 |
|  | 169 | 374/158.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/16 15:29 |

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| - | 1074 | 600/549.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/16 15:30 |
| - | 733  | 374/208.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/16 17:28 |
| - | 1074 | 600/549.ccls.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/16 17:34 |
| - | 450  | 600/549.ccls. and probe  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/16 17:35 |
| - | 218  | 600/549.ccls. and probe and (cover or sheath)  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/16 17:35 |
| - | 411  | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and (transparent or clear)         | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/17 09:58 |
| - | 244  | (374/208.ccls. or 374/183.ccls. or 600/549.ccls.) and (transparent)                  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/17 09:58 |
| - | 284  | (374/208.ccls. or 374/183.ccls. or 374/158.ccls. or 600/549.ccls.) and (transparent) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/04/17 09:59 |
| - | 2    | "20020181545"  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/23 14:51 |
| - | 0    | "20020181545" and (processor or microprocessor)                                      | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/23 14:51 |
| - | 1    | "20020181545" and (process\$3 or microprocess\$3)                                    | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/23 18:42 |
| - | 2    | "20020181545"  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/23 19:35 |

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| - | 20 | "4572365" | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/23 19:37 |
| - | 24 | "4619271" | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/23 20:47 |